CERTIFICATE OF CONFORMITY

Certificate no.:
C560125

Initial certification date:
28 September 2022

Valid:
28 September 2023 – 27 September 2024

This is to certify that the management system of

NEPES Corporation & NEPES Ark Cheongju 2 Campus

587-32, Gwahaksaneop 2-ro, Ochang-eup, Cheongwon-gu, Cheongju-si, Chungcheongbuk-do, 28116, Republic of Korea

and the sites as mentioned in the appendix accompanying this certificate

has been found to conform to Electrostatic Discharge Control Program:

ANSI/ESD S20.20-2021

This certificate is valid for the following scope:

Manufacture of Semiconductor Devices including Wafer Bumping(Au Solder Plating, Cu Pillar Bump, Redistribution Layer Thick Cu and Au Plating) Wafer Probing and Assembly Process.

The audit has been performed under the supervision of: Kyu Jun Hwang (Lead Auditor)
Client ESD Program Manager: Seung Won Lee

Place and date:
Katy, TX, 15 September 2023

For the issuing office:
DNV - Business Assurance
1400 Ravello Drive, Katy, TX, 77449-5164, USA

Chris Mauterstock
ESD Sector Lead

Lack of fulfilment of conditions as set out in the Certification Agreement may render this Certificate invalid.
ACCREDITED UNIT: DNV Business Assurance USA Inc., 1400 Ravello Drive, Katy, TX, 77449, USA - TEL: +1 281-396-1000. www.dnv.com

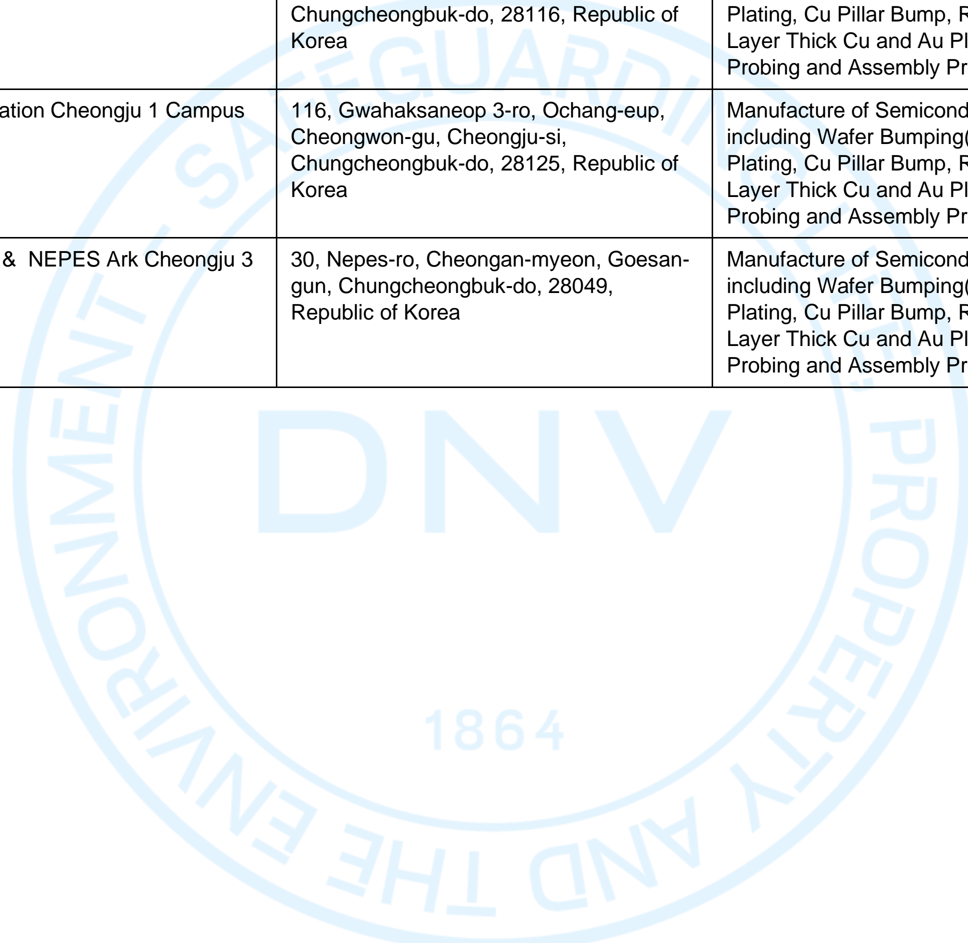
Certificate no.: C560125
Place and date: Katy, TX, 15 September 2023

Appendix to Certificate

NEPES Corporation & NEPES Ark Cheongju 2 Campus

Locations included in the certification are as follows:

Site Name	Site Address	Site Scope
NEPES Corporation & NEPES Ark Cheongju 2 Campus	587-32, Gwahaksaneop 2-ro, Ochang-eup, Cheongwon-gu, Cheongju-si, Chungcheongbuk-do, 28116, Republic of Korea	Manufacture of Semiconductor Devices including Wafer Bumping(Au Solder Plating, Cu Pillar Bump, Redistribution Layer Thick Cu and Au Plating) Wafer Probing and Assembly Process.
NEPES Corporation Cheongju 1 Campus	116, Gwahaksaneop 3-ro, Ochang-eup, Cheongwon-gu, Cheongju-si, Chungcheongbuk-do, 28125, Republic of Korea	Manufacture of Semiconductor Devices including Wafer Bumping(Au Solder Plating, Cu Pillar Bump, Redistribution Layer Thick Cu and Au Plating) Wafer Probing and Assembly Process.
NEPES Laweh & NEPES Ark Cheongju 3 Campus	30, Nepes-ro, Cheongan-myeon, Goesan-gun, Chungcheongbuk-do, 28049, Republic of Korea	Manufacture of Semiconductor Devices including Wafer Bumping(Au Solder Plating, Cu Pillar Bump, Redistribution Layer Thick Cu and Au Plating) Wafer Probing and Assembly Process.



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